

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3118807

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SENG KIM YE	11/21/2014
HONG WAN NG	11/21/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MICRON TECHNOLOGY, INC.
<b>Street Address:</b>	8000 S. FEDERAL WAY, P.O. BOX 6
<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83707-0006
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14550243
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(206)359-4209
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	206-359-8000
<b>Email:</b>	swhelan@perkinscoie.com
<b>Correspondent Name:</b>	PERKINS COIE LLP - MICRON PATENT-SEA
<b>Address Line 1:</b>	PO BOX 1247
<b>Address Line 4:</b>	SEATTLE, WASHINGTON 98111-1247
<b>ATTORNEY DOCKET NUMBER:</b>	10829-9123.US00
<b>NAME OF SUBMITTER:</b>	STEPHEN P. WHELAN
<b>SIGNATURE:</b>	/Stephen P. Whelan/
<b>DATE SIGNED:</b>	11/21/2014
<b>Total Attachments: 4</b>	
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### ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- Seng Kim Ye, having a mailing address of Block 311C, #05-32 Anchorvale Lane, Singapore 543311, Republic of Singapore; and
- Hong Wan Ng, having a mailing address of Block 75C, #24-76 Redhill Road, Singapore 153075, Republic of Singapore.

The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled MEMORY DEVICES WITH CONTROLLERS UNDER MEMORY PACKAGES AND ASSOCIATED SYSTEMS AND METHODS, naming the Assignors as inventors, and filed on \_\_\_\_\_ as U.S. Application No. \_\_\_\_\_ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

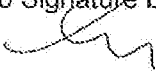
For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do


such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. This Assignment may be executed in counterparts.

Date: 11/6/2014

  
\_\_\_\_\_  
Hong Wan Ng

Witness to Signature by Hong Wan Ng:

  
\_\_\_\_\_  
Signature Chong Chin Hui  
Printed Name

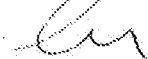
  
\_\_\_\_\_  
Signature Ong Yee Choon  
Printed Name


Date: 11/21/2014




\_\_\_\_\_  
Seng Kim Ye

Witness to Signature by Seng Kim Ye:

  
\_\_\_\_\_  
Signature  
Chong Chia Hui  
\_\_\_\_\_  
Printed Name

  
\_\_\_\_\_  
Signature  
Ong Yew Chon  
\_\_\_\_\_  
Printed Name

  
  
11/21/2014  
**PATENT**